

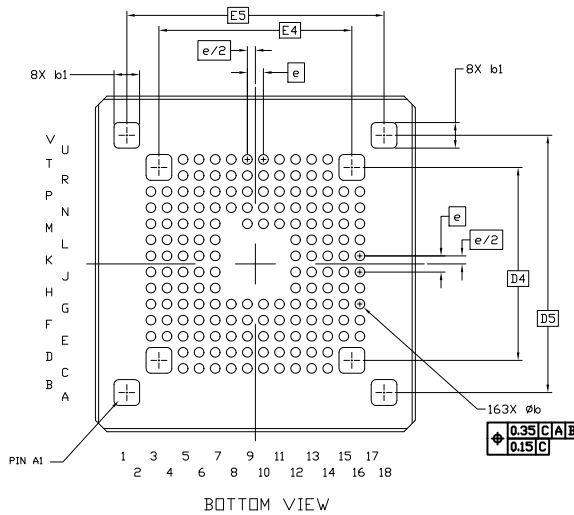
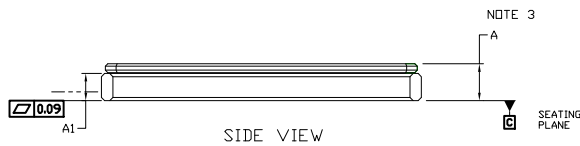
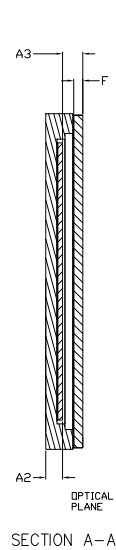
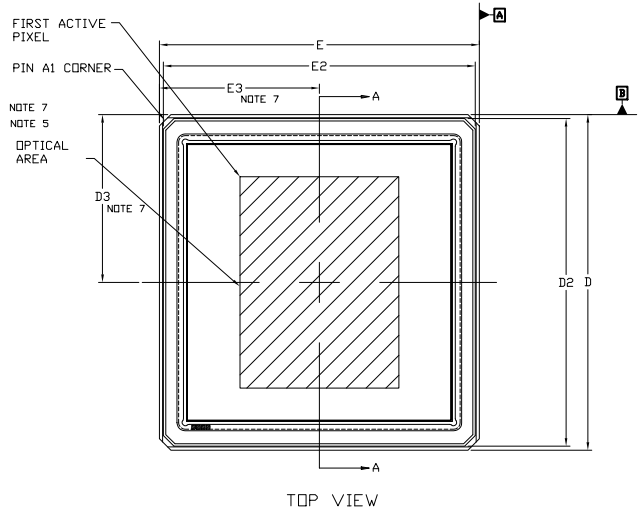
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



CLGA163 20.88x19.9, 1P CASE 621AB ISSUE A

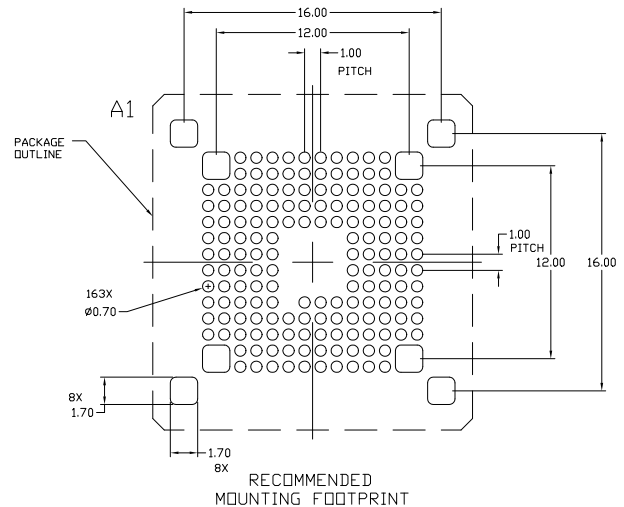
DATE 11 SEP 2018



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY AND LID BUT DOES NOT INCLUDE HEATSINKS OR OTHER ATTACHED FEATURES.
4. THE LID DEFINED BY DIMENSIONS D2 AND E2 MUST BE LOCATED WITHIN DIMENSIONS D AND E.
5. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO PACKAGE EDGES JOINING AT A1 CORNER, WILL BE 0.7°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATA SHEET FOR TOTAL ARRAY AND FIRST PIXEL DEFINITIONS.
6. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.
7. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X= 12.345 MICRONS, Y= 77.63 MICRONS ±200 MICRONS.

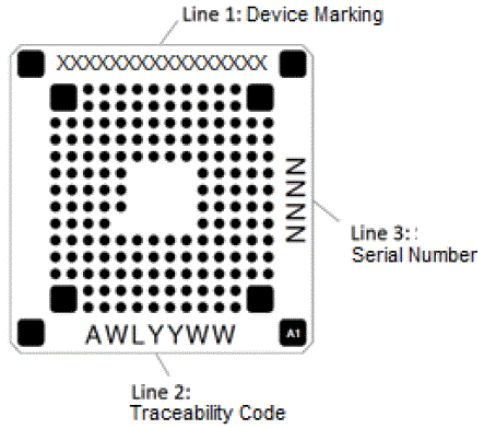
MILLIMETERS		
DIM	MIN.	MAX.
A	---	2.54
A1	1.61	1.89
A2	0.91	1.19
A3	1.05	1.45
b	0.55	0.65
b1	1.60	REF
D	20.76	21.00
D2	20.30	20.46
D3	10.16	10.56
D4	12.00	BSC
D5	16.00	BSC
E	19.80	20.00
E2	19.32	19.48
E3	9.76	10.16
E4	12.00	BSC
E5	16.00	BSC
e	1.00	BSC
F	0.50	0.60



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**GENERIC
MARKING DIAGRAM***



- XXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- NN = Serial Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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